



75ARM1 3U cPCI Single Board Computers

3U cPCI ARM Cortex-A9 SBC

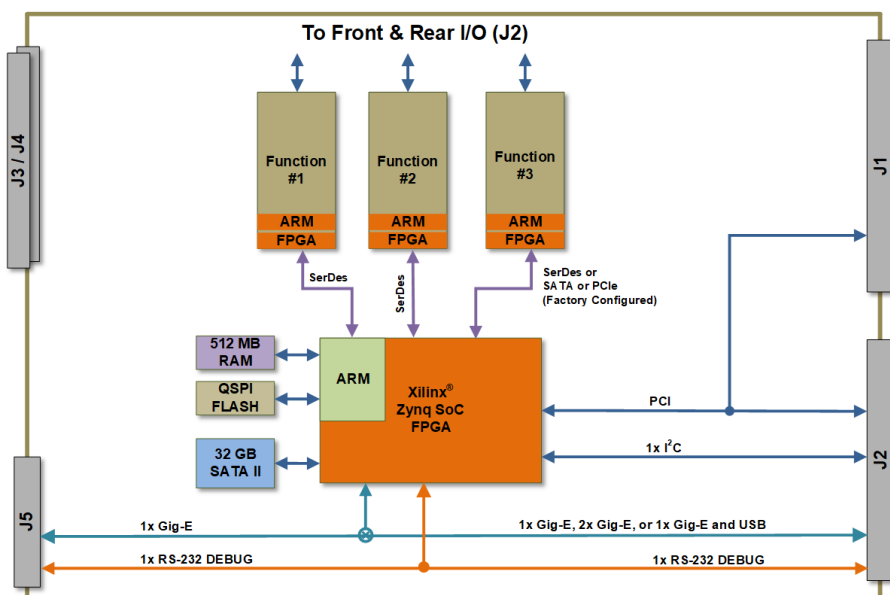
**3U cPCI ARM SBC with three I/O and communications function module slots—
Over 100 different modules to choose from**

NAI's 75ARM1 is a 3U cPCI ARM® Cortex®-A9 - based, Single Board Computer (SBC) that can be configured with up to three smart function modules. Ideally suited for rugged defense, commercial aerospace, and industrial applications, the 75ARM1 delivers off-the-shelf solutions that accelerate deployment of SWaP-optimized systems.

The ARM® Cortex®-A9 processor is a low power, cost-sensitive, multi-core processor delivering exceptional levels of performance and power efficiency with all the functionality required in rugged, embedded SWaP-optimized programs for the Defense and Aerospace industries.

The 75ARM1 includes BSP and SSK support for Wind River® VxWorks®, and for Xilinx® PetaLinux and DDC-I Deos. In addition, SSKs are supplied with source code and board-specific library I/O APIs to facilitate system integration.

Eliminate man-months of integration with a configured, field-proven 3U cPCI ARM® Cortex®-A9 SBC from NAI.



Features

- ARM® Cortex®-A9 Dual Core 800MHz Processor
- 512 MB DDR3 SDRAM
- Up to 32 GB SATA II NAND Flash (256 GB expansion option in slot #3)
- < 5 W MB power dissipation
- Up to 3 independent smart I/O function modules supported
- Front and/or rear I/O
- 100+ modules to choose from
- Commercial or rugged applications
- Independent x1 SerDes interface to each function module slot
- 2x 10/100/1000 Base-T Ethernet; 2 to rear or 1 to rear and 1 to front I/O
- 1x RS-232 to front or rear I/O
- I2C Bus to rear I/O
- Wind River® Linux, VxWorks®, Xilinx® PetaLinux, and DDC-I Deos™ OS support
- Continuous Background Built-in-Test (BIT)
- Intelligent I/O library support included
- COSA® Architecture
- VICTORY Interface Services (Contact factory)
- Operating temp: 0° C to +70° C or Rugged -40° C to +85° C

Select up to 3 independent functions for your application

I/O Modules					
Function	Module	Description	Function	Module	Description
Analog-to-Digital	AD1	12 CH. A/D, ± 10 V, Dedicated, 256 kHz (max), Sigma-Delta	Digital-to-Analog	DA5	4 CH. D/A, High-Voltage/High-Current Half-Bridge (2 Channels Full-Bridge) External VCC Sourced Outputs
	AD2	12 CH. A/D, ± 100 V (max), Dedicated, 256 kHz (max), Sigma-Delta	Digital IO - Differential Transceiver	DF1	16 CH. Differential I/O, Input: -10 V to +10 V (422), -7 V to +12 V (485) Output: -25 V to +5 V
	AD3	12 CH. A/D, ± 25 mA, Dedicated, 256 kHz (max), Sigma-Delta		DF2	16 CH. 16 Channel Enhanced Differential I/O
	AD4	16 CH. A/D, ± 10 V, Multiplexed, 500 KHz Agg / 8 Ch, SAR	Discrete IO - Multichannel, Programmable	DT1	24 CH. Discrete I/O, 0-60 VDC Input/Output, Max Iout 500 mA - 2 A, Source/Sink (out)
	AD5	16 CH. A/D, ± 50 V, Multiplexed, 500 KHz Agg / 8 Ch, SAR		DT2	16 CH. Discrete I/O, ± 80 V Input/Output, Max Iout 600 mA, Isolated/Ch Switch (out)
	AD6	16 CH. A/D, ± 100 V, Multiplexed, 500 KHz Agg / 8 Ch, SAR		DT3	4 CH. Discrete Hi & Lo Side Switch Output @ 65V/2A (max), external individual supplied VCC & VSS per channel pair
	ADE	16 CH. A/D, ± 10 V, Individual 16-bit SAR, 200 kHz max., Simultaneous Sampling		DT4	24 CH. Enhanced DT1
	ADF	16 CH. A/D, ± 100 V, Individual 16-bit SAR, 200 kHz max., Simultaneous Sampling		DT5	16 CH. Enhanced DT2
Chip Detector and Fuzz Burn	CD1	6 CH. Chip Detector (CD) and Fuzz Burn (FB)	Relay	RY1	4 CH. Relay, 220V/2A @ 60W/62.5VA (Max), Non Latching
Digital-to-Analog	DA1	12 CH. D/A, ± 10 V, 25 mA Per Channel, Current or Voltage Control		RY2	4 CH. Relay, 220V/2A @ 60W/62.5VA (Max), Latching
	DA2	16 CH. D/A, ± 10 V, 10 mA Per Channel, No Current Control	Digital IO - TTL, CMOS	TL1	24 CH. TTL I/O, Standard Functionality, Programmable
	DA3	4 CH. D/A, ± 40 V, ± 100 mA, Voltage or Current Output		TL2	24 CH. TTL I/O, Enhanced Functionality, Programmable
	DA4	4 CH. D/A, ± 20 to ± 80 , 10 mA, Voltage Control Only	Variable Reluctance	VR1	8 CH. Variable Reluctance Signal Input and General-Purpose Pulse Counter, ± 100 V, 100 kHz (max)
Measurement & Simulation Modules					
Function	Module	Description	Function	Module	Description
AC Reference	AC2	2 CH. AC Reference Source, 47 Hz - 20 KHz, $\pm 3\%$ Acc, 2 - 28 Vrms, 6 VA (Max/Ch) Power	Synchro Resolver Measurement and Simulation	DSx (DRx)	1 - 3 CH. Digital to Synchro/Resolver, 2 - 90 VLL, 2 - 1115 Vrms Exc, 47 Hz - 20 kHz Freq
	AC3	2 CH. AC Reference Source, 47 Hz - 2.5 KHz, $\pm 3\%$ Acc, 28 - 115 Vrms, 6 VA (Max/Ch) Power		SDx	4 CH. Synchro/Resolver to Digital, 2 - 90 Vrms Input, 2 - 115 Vrms Exc, 47 Hz to 20 kHz Freq
LVDT RVDT Measurement and Simulation	DLx	1 - 3 CH. Digital to LVDT/RVDT, 2 - 90 Vrms Full Scale, 2 - 115 Vrms Exc, 47 Hz - 20 kHz Freq	Pulse Timer Receiver and Generator	PT1	2 CH. Pulse Timer 1-PPS &/or 10 MHz Input with Multiple Outputs and 2 Channels Isolated RS-422/485 Serial Communications
	LD1	4 CH. LVDT/RVDT to Digital, 2-28 Vrms Input, 2-115 Vrms Exc, 47 Hz - 1 KHz Freq	IRIG Timecode Receiver and Generator	RG1	1 CH. IRIG Timing Function Interface
	LD2	4 CH. LVDT/RVDT to Digital, 2-28 Vrms Input, 2-115 Vrms Exc, 1 KHz - 5 KHz Freq	Thermocouple and RTD Measurement	RT1	8 CH. Resistance Temperature Detectors (RTD), 2, 3, or 4 wire, 16 Bit Res, 16.7 Hz/Ch
	LD3	4 CH. LVDT/RVDT to Digital, 2-28 Vrms Input, 2-115 Vrms Exc, 5 KHz - 10 KHz Freq		TC1	8 CH. Thermocouple, 4.17 - 470 Hz, ± 100 mV A/D
	LD4	4 CH. LVDT/RVDT to Digital, 2-28 Vrms Input, 2-115 Vrms Exc, 10 KHz - 20 KHz Freq		TR1	8 CH. Thermocouple (TCx) & Resistance Temperature Detectors (RTD), programmable per channel
	LD5	4 CH. LVDT/RVDT to Digital, 28-90 Vrms Input, 2-115 Vrms Exc, 47 Hz - 1 KHz Freq	Strain Gauge Measurement	SG1	4 CH. Strain Gauge, 4.7 Hz - 4.8 KHz, Measurement, Conventional 4-Arm Bridge

Communication Modules					
Function	Module	Description	Function	Module	Description
ARINC Communications	<u>AR1</u>	12 CH. ARINC 429, 100 KHz or 12.5 KHz, RX/TX, 256 Word Tx/Rx Buffer	MIL-STD-1553B	<u>FTE</u>	2 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Direct Coupled
	<u>AR2</u>	1 CH. ARINC 568 (CH-1, RX & TX) & 1 Channel ARINC 579 (CH-2, Programmable RX or TX), 1024-Word TX & RX Buffers per Ch.		<u>FTF</u>	4 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Direct Coupled
CANBus Communications	<u>CB1</u>	8 CH. CANBus, CAN 2.0 A/B, 16 K RX/TX Buffer, 1 Mb/s Max Data Rate	MIL-STD-1760	<u>FTJ</u>	1 CH. MIL-STD-1760 (1553), BC, RT, BM, BM/RT, 128 KB RAM, Transformer Coupled
	<u>CB2</u>	8 CH. CANBus, J1939, 16 K RX/TX Buffer, 500 kb/s Max Data Rate		<u>FTK</u>	2 CH. MIL-STD-1760 (1553), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Transformer Coupled
	<u>CB3</u>	8 CH. CANBus, CAN 2.0 A/B (CB1) or J1939 (CB2) protocol layer programmable per channel	IEEE 1394 (FireWire)	<u>FW1</u>	2 CH. (nodes), IEEE 1394b (Firewire), tri-port per channel, including TLIM
Ethernet NIC Interface	<u>EM1</u>	2 CH. Dual Ethernet I/F, Intel 82850, 10/100/1000		<u>FW2</u>	2 CH. (nodes), IEEE 1394b (Firewire), tri-port per channel, direct (no TLIM)
MIL-STD-1553B	<u>FTA</u>	1 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM, Transformer Coupled	Serial Communications	<u>SC1</u>	4 CH. Serial, RS-232/422/423 (MIL-STD-188C)/485, Non Isolated
	<u>FTB</u>	2 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Transformer Coupled		<u>SC3</u>	8 CH. (max) RS-232/422/485 Serial Communications or GPIO, Programmable, Non-isolated
	<u>FTC</u>	4 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Transformer Coupled		<u>SC5</u>	4 CH. RS-232/422/485 communications, isolated per channel and from SYS GND
	<u>FTD</u>	1 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM, Direct Coupled		<u>SC6</u>	4 CH. RS-232/422/485 communications, individual SYS GND provided per channel (non-isolated)
Storage					
Function	Module	Description	Function	Module	Description
SATA Solid State Drive (SSD)	<u>FM2</u>	1 CH. 480 GB MLC SATA Flash, extended temp -40°C to 85°C operation	SATA Solid State Drive (SSD)	<u>FM8</u>	1 CH. 1 TB SATA TLC NAND Flash, Extended Temperature Operation
	<u>FM7</u>	1 CH. 1 TB SATA Flash, 3D NAND MLC, 0-70 °C operation		<u>FM9</u>	1 CH. 1.92 TB SATA TLC NAND Flash, Extended Temperature Operation
Combination Modules					
Function	Module	Description	Function	Module	Description
Combo	<u>CM5</u>	2 CH. Dual-redundant MIL-STD-1553 & 8 Channel ARINC 429/575, 100 KHz or 12.5 KHz, RX or TX, 256 Word Tx/Rx Buffer	Combo	<u>CM8</u>	2 CH. Dual-redundant MIL-STD-1553 & 12 Channel Discrete I/O, 0-60 VDC Input/Output, Max Iout 500 mA - 2 A, Source/Sink (out)

Architected for Versatility

NAI's Configurable Open Systems Architecture™ (COSA®) offers a choice of over 100 smart I/O, communications, or Ethernet switch functions, providing the highest packaging density and greatest flexibility of ruggedized embedded product solutions in the industry. Preexisting, fully-tested functions can be combined in an unlimited number of ways quickly and easily.

One-Source Efficiencies

Eliminate man-months of integration with a configured, field-proven system from NAI. Specification to deployment is a seamless experience as all design, state-of-the-art manufacturing, assembly and test are performed - by one trusted source. All facilities are located within the U.S. and optimized for high-mix/low volume production runs and extended lifecycle support.

Product Lifecycle Management

From design to production and beyond, NAI's product lifecycle management strategy ensures the long-term availability of COTS products through configuration management, technology refresh and obsolescence component purchase and storage.

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